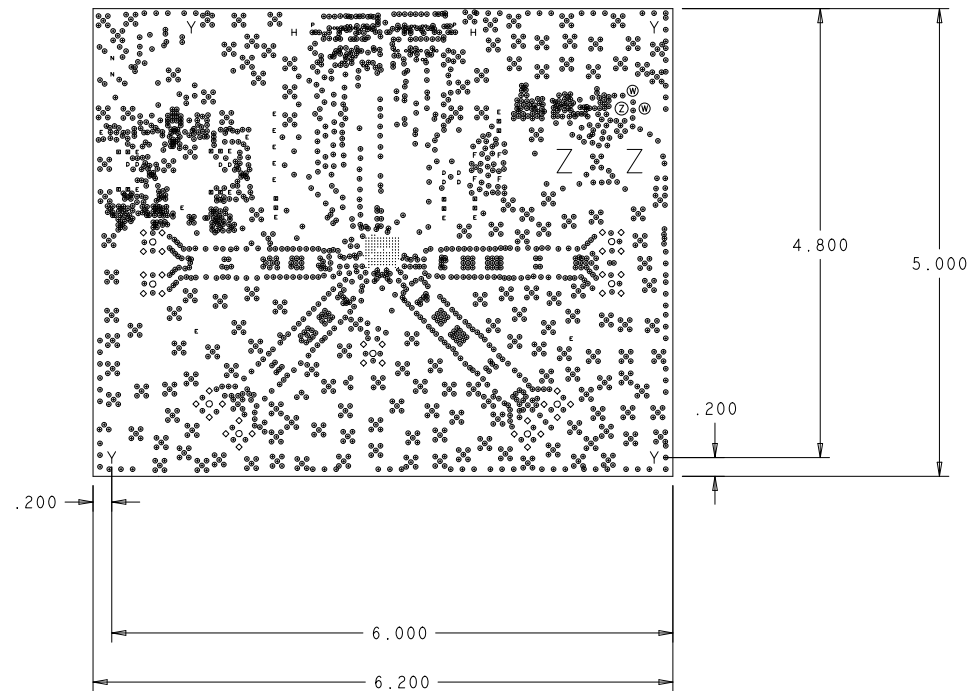
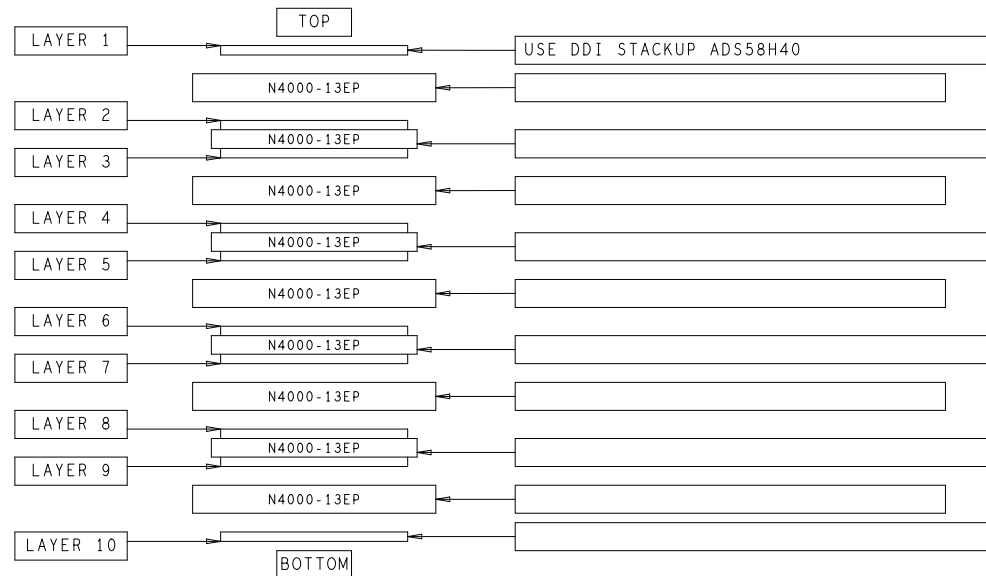


UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
2. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/- .003.
3. REGISTRATION TOLERANCE: ARTWORK +/- .002
 ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
BOARD MATERIAL SHALL BE 180TG/340TD NELCO 4000-13EP
BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B.
RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.

MATERIAL: MULTILAYER
COPPER THICKNESS: .062 +/- .006
BOARD THICKNESS: .062 +/- .006
NUMBER OF FINISHED LAYERS: 10
6. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN COPPER/SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
7. SOLDERMASK: HASL. COLOR = RED.
8. SILKSCREEN BOTH SIDES, USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE +/- .005.
9. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
10. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
11. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS.
12. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
13. ALL INNER LAYER THERMALS ON 8 AND 10MIL HOLES TO BE CHANGED TO DIRECT TIES TO THE PLANE LAYERS.
14. TOP AND BOTTOM LAYERS 12 MIL TRACES TO BE 50 OHM IMPEDANCE.
TOP AND BOTTOM LAYERS 6 MIL TRACES WITH 6 MIL SPACING TO BE 100 OHM DIFFERENTIAL IMPEDANCE.
INNER LAYERS 5 MIL TRACES WITH 7 MIL SPACING TO BE 100 OHM DIFFERENTIAL IMPEDANCE.
15. MINIMUM COPPER CONDUCTOR WIDTH IS : 5 MILS.
MINIMUM COPPER SPACING IS: 4 MILS.
16. SMOBC/IMMERSION GOLD: 2-8 uIN OVER 118-236 uIN PLATING.
17. PADS MAY BE TEAR-DROPPED TO MEET THE ANNUAL RING REQUIREMENTS.
18. PCB MUST BE RoHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY,
MAX REFLOW OF 260 DEGREES C (6 PASSES).
19. ALL 6 MIL, 8 MIL AND 10 MIL HOLES/VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY. FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANAR.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
·	6.0	PLATED	121
•	8.0	PLATED	38
•	10.0	PLATED	224
•	38.0	PLATED	8
•	40.0	PLATED	18
■	40.0	PLATED	16
•	51.0	PLATED	4
○	62.0	PLATED	9
◇	67.0	PLATED	36
H	68.0	PLATED	2
⊗	120.0	PLATED	2
⊙	140.0	PLATED	1
Z	250.0	PLATED	2
"	39.0	NON-PLATED	2
"	40.0	NON-PLATED	2
Y	125.0	NON-PLATED	4

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.				
	APPROVALS	DATE	FABRICATION DRAWING ADS58H40 EVM				
	DRAWN JV SMITH	11-11-11					
	ENGR K HSIA	11-11-11					
MATERIAL SEE NOTE 5			SIZE	CODE	IDENT NO.	DRAWING NO.	REV.
FINISH SEE NOTES 7, 8, 9			B				C
DO NOT SCALE DRAWING			SCALE	NONE		SHEET 1 OF 1	